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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICATION FOR LETTERS PATENT

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**SEMICONDUCTOR PROCESSOR SYSTEMS,
SYSTEMS CONFIGURED TO PROVIDE A
SEMICONDUCTOR WORKPIECE PROCESS
FLUID, SEMICONDUCTOR WORKPIECE
PROCESSING METHODS, METHODS OF
PREPARING SEMICONDUCTOR WORKPIECE
PROCESS FLUID, AND METHODS OF
DELIVERING SEMICONDUCTOR WORKPIECE
PROCESS FLUID TO A SEMICONDUCTOR
PROCESSOR**

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1 SEMICONDUCTOR PROCESSOR SYSTEMS, SYSTEMS
2 CONFIGURED TO PROVIDE A SEMICONDUCTOR WORKPIECE
3 PROCESS FLUID, SEMICONDUCTOR WORKPIECE PROCESSING
4 METHODS, METHODS OF PREPARING SEMICONDUCTOR
5 WORKPIECE PROCESS FLUID, AND METHODS OF DELIVERING
6 SEMICONDUCTOR WORKPIECE PROCESS FLUID TO A
7 SEMICONDUCTOR PROCESSOR



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6 RELATED PATENT DATA

7 The present application is a continuation-in-part of Patent
8 Application Serial No. 09/324,737 which was filed on June 3, 1999 and
9 which is incorporated by reference herein.

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10 TECHNICAL FIELD

11 The present invention relates to semiconductor processor
12 systems, systems configured to provide a semiconductor workpiece process fluid,
13 semiconductor workpiece processing methods, methods of preparing
14 semiconductor workpiece process fluid, and methods of delivering
15 semiconductor workpiece process fluid to a semiconductor processor.

17 BACKGROUND OF THE INVENTION

18 Numerous semiconductor processing tools are typically utilized
19 during the fabrication of semiconductor devices. One such common
20 semiconductor processor is a chemical-mechanical polishing (CMP)
21 processor. A chemical-mechanical polishing processor is typically used
22 to polish or planarize the front face or device side of a semiconductor
23 wafer. Numerous polishing steps utilizing the chemical-mechanical